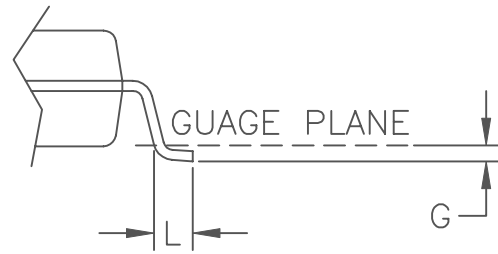
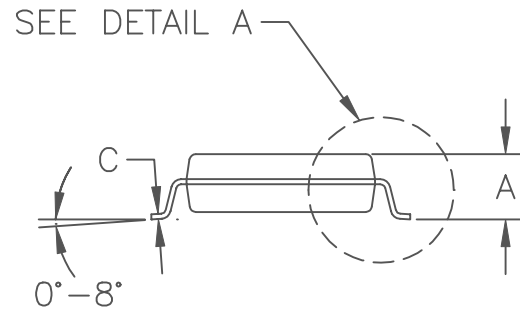
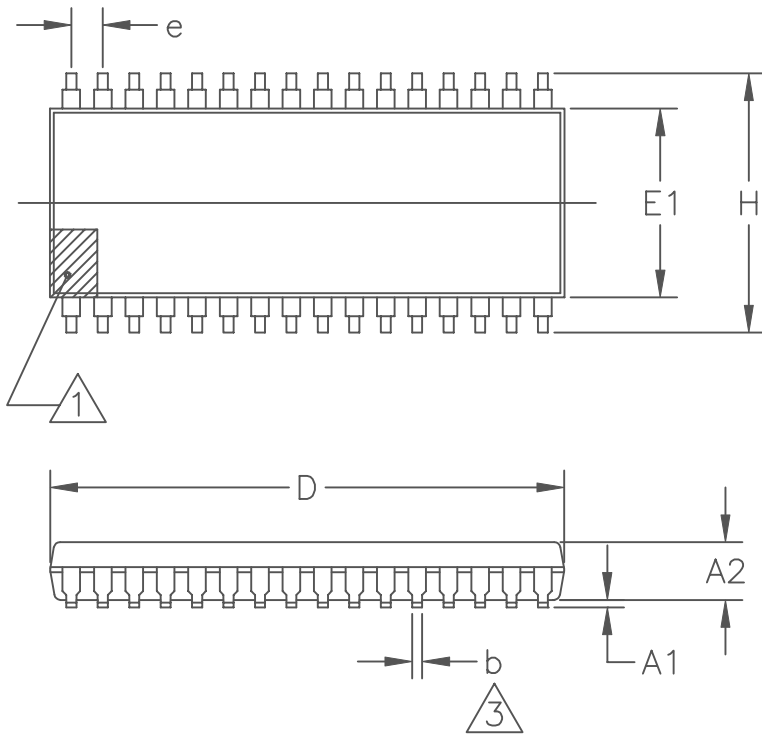


REVISIONS			
LTR	DESCRIPTION	DATE	APPROVED
A	NEW DRAWING		



DETAIL A

LTR	MIN	MAX
A IN. MM	— —	.104 2.64
A1 IN. MM	.004 .102	— —
A2 IN. MM	.082 2.08	.094 2.39
b IN. MM	.014 0.36	.020 0.51
C IN. MM	.006 0.15	.013 0.33
D IN. MM	.810 20.57	.824 20.93
e IN. MM	.050 BSC 1.27 BSC	
E1 IN. MM	.292 7.42	.299 7.59
H IN. MM	.405 10.29	.419 10.64
L IN. MM	.021 0.53	.041 1.04
G IN. MM	.014 BSC 0.36 BSC	

NOTES:

- 1 A TERMINAL 1 IDENTIFIER MUST BE POSITIONED SO THAT 1/2 OR MORE OF IT'S AREA IS CONTAINED IN THE HATCHED ZONE.
- 2 "D" AND "E1" DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS, BUT DOES INCLUDE MOLD MISMATCH AND ARE MEASURED AT THE MOLD PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .003 INCHES PER SIDE.
- 3 DIMENSION "b" IS MEASURED BELOW THE LOWER RADIUS OF THE FOOT.



DALLAS
SEMICONDUCTOR



SIGNATURE	DATE
DOC. CONTROL:	
ENGR. MGR: M. STRITTMATTER	1/98
MFG. ENGR: B. MCCARTY	9/97
CHECKED BY: R. RADKE	9/97
DRAWN BY: R.W.E.	9/97

TITLE

MARKETING OUTLINE—
.300" SOIC 32 LEAD .050" PITCH

SIZE

A

FSCM NO

PART NO.

56-G4009-032

REV

A

DO NOT SCALE DWG.

SCALE N/A

SHEET 1 OF 1